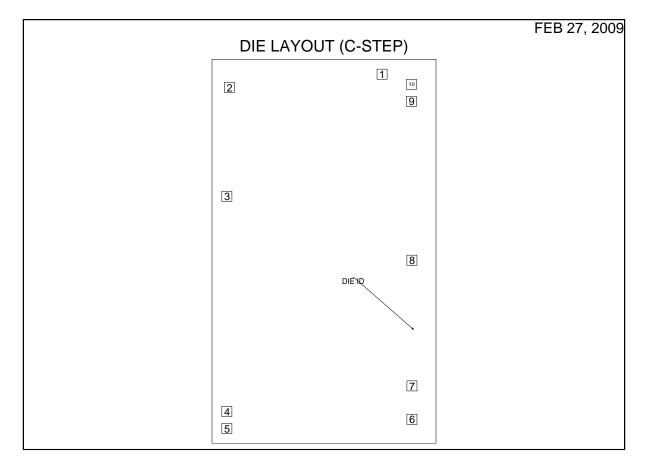


LM6172 MDR MCD3010A

DUAL HIGH SPEED, LOW POWER, LOW DISTORTION VOLTAGE FEEDBACK



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information		
Physical Die	LM6172C	Bond Pad Opening	80.00µm x 80.00µm	
Identification		Size (min)		
Die Step	С	Bond Pad Metalization	AL 0.5%CU	
Physical Attributes		Passivation	PECVDOX NITRIDE	
Wafer Diameter	150mm	Back Side Metal	BAREBACK	
Die Size (Drawn)	1778.0µm x 3048.0µm	Back Side Connection	Floating	
	70.0mils x 120.0mils			
Thickness	304.8µm Nominal			
Min Pitch	135µm			
Note: All values are roun	ded to the nearest micron			
Special Assembly Requir	ements:			



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Signal Name	Pad Number	X/Y Coordinates		Pad Size		
-		Х	Y	Х		Y
OUTPUT A	1	461	1406	80	Х	80
INPUT A-	2	-751	1301	80	х	80
INPUT A+	3	-771	437	80	х	80
V-	4	-771	-1271	80	х	80
V-	5	-771	-1406	80	х	80
INPUT B +	6	698	-1333	80	х	80
INPUT B -	7	698	-1068	80	х	80
OUTPUT B	8	698	-71	80	х	80
V+	9	695	1191	80	х	80
V+	10	695	1326	80	х	80



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